

Name	Multilayer Power Inductors	СОМРО	SITE SPECIFICATION	1/
	CMLM2520C2R2MIT	SPEC#	CMLM2520C2R2MIT	/ 9

### 1. Scope

This specification applies to the CMLM2520C2R2MIT series Multilayer Power Inductors

### 2. Standard and Atmospheric Conditions

Unless otherwise specified the standard range of atmospheric conditions for making measurements and tests is as follows:

Ambient temperature :  $20\pm15^{\circ}$ C Relative humidity :  $30\sim70\%$ 

If there may be any doubt on the results, measurements shall be made within

the following limits:

Ambient temperature : 25±5 °C Relative humidity : 30~70%

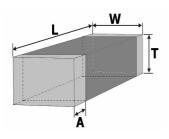
### 3. Ratings

PART NO	INDUCTANCE AT1 MHz 250mV	SELF-RESONANT FREQUENCY(MHz)	DC RESISTANCE $(\Omega)$	RATED CURRENT  (mA)Max
		Min	(22)	(III/A)IVIAX
CMLM2520C2R2MIT	2.2uH± 20%	40	0.08±25%	1300

%The maximum rated current : the DC current value having temperature increased 40  $\,^{\circ}$ C after thru DC current 2 hours at ambient temperature.

Regarding to the inductance variability of rated current, please refer to page 2: Inductance Vs. DC superposition characteristics.

### 4. Dimensions



unit:

OPERATING TEMP. RANGE: $-55^{\circ}$ C ~ $+125^{\circ}$ C							
STORAGE TEMP. RANGE: -10 $^{\circ}$ C ~ +40 $^{\circ}$ C							
TYPE L W T				A(m/m)			
CMLM2520	2.5±0.2	2.0±0.2	0.9±0.1	0.5±0.3			

PLANNED BY	CHECKED BY	APPROVED BY
LUN	TINA	Chi Chi Huang

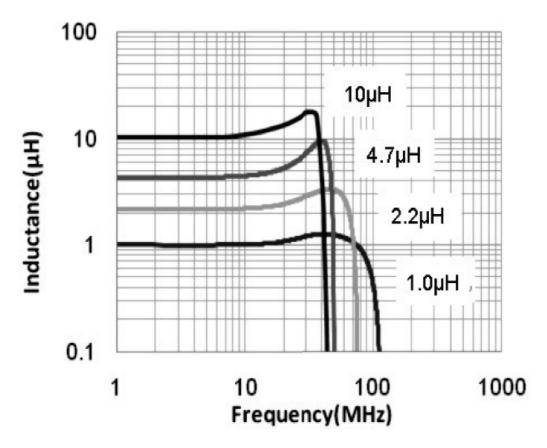




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Reference curve

### Inductance vs. Frequency Characteristics

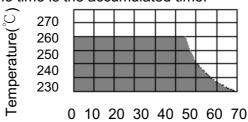




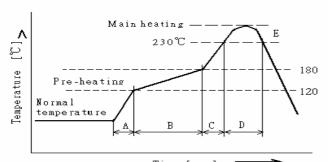
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### 6. Reflow soldering conditions

- Pre—heating should be in such a way that the temperature difference between solder and ferrite surface is limited to 150°C max. Also cooling into solvent after soldering should be in such a way that the temperature difference is limited to 100°C max.
   Insufficient pre—heating may cause cracks on the ferrite, resulting in the deterioration of product quality.
- Products should be soldered within the following allowable range indicated by the slanted line. The excessive soldering conditions may cause the corrosion of the electrode, when soldering is repeated, allowable time is the accumulated time.



#### **Temperature Profile**



Α	Slope of temp. rise	1 to 5	°C/sec
В	Heat time	50 to 150	sec
Б	Heat temperature	120 to 180	°C
С	Slope of temp. rise	1 to 5	°C/sec
D	Time over 230℃	90~120	sec
Е	Peak temperature	255~260	°C
L	Peak hold time	10 max.	sec
	No. of mounting	3	times

Time [sec] (Melting area of solder)

6-1 Reworking with soldering iron

Preheating	150°ℂ, 1 minute
Tip temperature	280°C max.
Soldering time	3 seconds max.
Soldering iron output	30w max.
End of soldering iron	φ 3mm max.

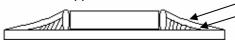
• Reworking should be limited to only one time.

Note: Do not directly touch the products with the tip of the soldering iron in order to prevent the crack on the ferrite material due to the thermal shock.

6-2 Solder Volume

Solder shall be used not to be exceed the upper limits as shown below.

Upper Limit Recommendable



Accordingly increasing the solder volume, the mechanical stress to product is also increased. Exceeding solder volume may cause the failure of mechanical or electrical performance.



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### 7. Equipment

7-1 Inductance

Inductance shall be measured with HP -4286A Inductance analyzer or equivalent system

7-2 DC RESISTANCE

DC resistance shall be measured using HP 4338 digital mili — ohm meter with 4 terminal method.

### 8. Mechanical Characteristics

ITEM	Specification	Test Conditions
Terminal	Without deformation cases	Solder chip on PCB and applied 10N
Strength	inductance shall be satisfied ± 20%	(1.02Kgf) for 10 sec
	DC resistance shall be satisfied.	CHIP  Okar Spore PCB
Substrate	Without deformation cases,	After soldering a chip to a test substrate,
Bending Test	inductance shall be satisfied ± 20%	bend the substrate by 3mm hold for 10s
	DC resistance shall be satisfied.	and then return.
		Soldering shall be done in accordance
		with the recommended PC board pattern
		and reflow soldering.
		unit : mm  45 45 45 100
Resistance	No visible damage	Solder Temp. : 265±3℃
to Solder Heat	Electrical characteristics and mechanic	Immersion time : 6±1 sec
	characteristics shall be satisfied.	Preheating : $100^{\circ}$ C to $150^{\circ}$ C, 1 minute.
		Measurement to be made after keeping at room
	Consult standard MIL-STD-202	temp for 24±2 hrs.
	METHOD 210	Solder : Sn-3Ag-0.5Cu
Solderability	95% min. coverage of all	Solder temp. : 240±5℃
	metabolised area	Immersion time : 3±1 sec
		Solder : Sn-3Ag-0.5Cu
	Consult standard J-STD-002	



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9. 1	RELIABILITY AND TEST CONDITIONS 9-1 HIGH TEMPERATURE RESISTANCE a. Performance specification 1.Appearance: no mechanical damage 2.Inductance shall be with ±20% of the initial valu b.Test condition 1.Temperature: 125°C ±2°C 2.Testing time: 1000±12hrs 3.Measurement: After placing at room ambient to 9-2 Biased Humidity RESISTANCE a.Performance specification 1.Appearance: no mechanical damage		for 24 hours minimum
	2.Inductance shall be with ±20% of the initial valu b.Test condition 1.Humidity: 85 ± 5%RH 2. Temperature: 85°C ±2°C 3.Testing time: 1000 ± 12 hours 4.Measurement: After placing at room ambient t		for 24 hours minimum
	9-3 TEMPERATURE CYCLE a.Performance specification 1.Appearance: no mechanical damage 2.Inductance shall be with ±20% of the initial value b.Test condition 1. Low Temperature: - 55°C ±5°C kept stabilized	e for 30 minute	es each
	<ol> <li>High Temperature: 125°C ±5°C kept stabilized ff</li> <li>Cycle: 1000 cycles</li> <li>Measurement: After placing for 24hours minime</li> <li>step155°C temp±3°C 30±3 minutes</li> <li>step2. Room temperature 2to5 minutes</li> <li>step3. +125°C temp±3°C 30±3 minutes</li> <li>step4. room temperature 2to5 minutes</li> </ol>		
	9-4 VIBRATION TEST a.Performance specification 1.Appearance: no mechanical damage 2.Inductance shall be with ±20% of the initial valu b.Test condition 1.Frequency and Amplitude:10-2000-10Hz 2.Direction:X,Y,Z.		
	3.Test duration:4 hours for each direction,12hour 9-5 Mechanical Shock TEST a.Performance specification 1.Appearance: no mechanical damage 2.Inductance shall be with ±20% of the initial valu b.Test condition 1.peak acceleration: 100 g's 2.Duration of pulse: 6 ms		
	3.Waveform: Half-sine 4.Velocity change: 12.3 ft/sec 5. Direction: X, Y, Z (3axes/3 times) 9-6 Operational Life a. Performance specification 1.Appearance: no mechanical damage 2.Inductance shall be with ±20% of the initial value.	e	
	1.Temperature: 125°C ±2°C 2.Testing time: 1000±12hrs 3.Measurement: After placing at room ambient t 9-7 Electrostatic discharge test a. Performance specification 1.Appearance: no mechanical damage 2.Inductance shall be with ±20% of the initial valu b.Test condition 1.ESD voltage: 15k volts	·	for 24 hours minimum
	2.Mode 1:150 pF/330 Ohm		

The reliability test customers if there are special requirements in accordance with customer needs

3.Mode 2:150 pF/2000 Ohm

9.1 REMARK

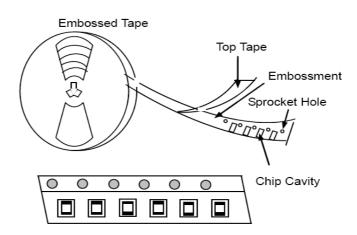


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#### 10.PAPER CARRIER TYPE PACKING

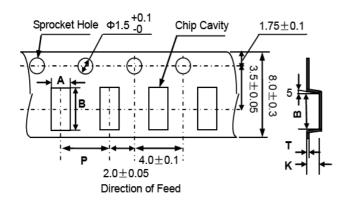
(1) Taping Drawings (Unit: mm)

Туре	2520
T (mm)	0.9±0.1
Таре	Embossed Tape
Quantity	3K



Remark: The sprocket holes are to the right as the tape is pulled toward the user.

#### (2) Taping Dimensions (Unit: mm)



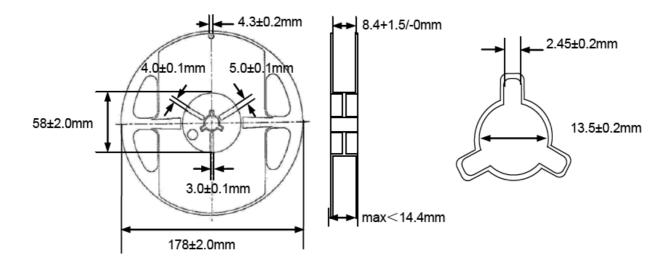
Туре	Α	В	Р	Kmax	Tmax	
CMLM2520	2.30±0.1	2.80±0.1	4.0±0.1	1.45	0.3	



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### 10.PAPER CARRIER TYPE PACKING

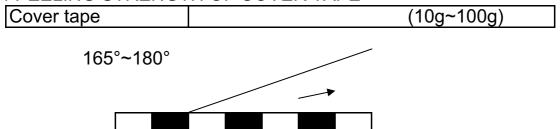
(3)Reel Dimensions(Unit:mm)





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### 10-4 PEELING STRENGTH OF COVER TAPE



Test condition

1. peel angle: 165°~180° vs carrier tape

2. peel speed: 300mm/min

### 11. Packaging

- 1. Tape & Reel packaging in composite specification 6/8
- 2) Reel and a bag of desiccant shall be packed in Nylon or plastic bag
- 3) Maximum of 5 reels shall be packaged in a inner box
- 4) Maximum of 6 inner box shall be packaged in a outer box

#### 12. Reel Label

Producing the goods label needs to indicate (1) Pb Free (2) RoHS Compliant



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### 13. Storage

- 13-1The solderability of the external electrode may be deteriorated if packages are stored where they are exposed to high humidity. Packages must be stored at 40°C or less and 70% RH or less.
- 13-2 The solderability of the external electrode may be deteriorated if packages are stored where they are exposed to dust or harmful gas (hydrogen chloride, sulfurous acid gas or hydrogen sulfide).
- 13-3 Packaging material may be deformed if packages are stored where they are exposed to heat or direct sun light.
- 13-4 Minimum packages, such as polyvinyl heat—seal packages shall not be opened until just before they are used.

  If opened, use the reels as soon as possible.
- 13-5 Solderability specified in composite specification 4/8 shall be for 6 months from the date of delivery on condition that they are stored at the environment specified clause 13-1 & 13-2.

For those parts which passed more than 6 months shall be checked solderability before it is used.